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Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-981	SERIAL NO. 09/148,723		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Farnworth et al.			
				FILING DATE 09/03/98	GROUP 3729		
PATENT DOCUMENTS EXAMINER & TRADEMARK OFFICE							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
AA							
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FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
AL						Yes	No
AM							
AN							
AO							
AP							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
<i>W</i>	AR	Kasulke, P., et al., "Solder Ball Bumper (SBB) - A Flexible Equipment for FC, CSP, BGA and Printed Circuit Boards", "An Innovative Solution for Solder Application Solder Ball Bumper (SBB)". Pac Tech Packaging Technologies GmbH and					
		Fraunhofer IZM, pp. 1-8.					
	AS						
	AT						
EXAMINER <i>A. Dastin Tugbana</i>		DATE CONSIDERED <i>12/3/99</i>					
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